Sebastian Engelmann

List of Publications by Year
in descending order

18	452	1937685 4	1872680 6
papers	citations	h-index	g-index

18	18	18	505
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Experimental realization of deep-subwavelength confinement in dielectric optical resonators. Science Advances, 2018, 4, eaat2355.	10.3	117
2	A Novel Approach to Photonic Packaging Leveraging Existing High-Throughput Microelectronic Facilities. IEEE Journal of Selected Topics in Quantum Electronics, 2016, 22, 455-466.	2.9	77
3	Understanding the Roughening and Degradation of 193â€‰nm Photoresist during Plasma Processing: Synergistic Roles of Vacuum Ultraviolet Radiation and Ion Bombardment. Plasma Processes and Polymers, 2009, 6, 649-657.	3.0	61
4	An O-band Metamaterial Converter Interfacing Standard Optical Fibers to Silicon Nanophotonic Waveguides. , 2015, , .		50
5	Assembly of mechanically compliant interfaces between optical fibers and nanophotonic chips. , 2014, , .		25
6	Automated, self-aligned assembly of 12 fibers per nanophotonic chip with standard microelectronics assembly tooling. , 2015, , .		18
7	Optical Demonstration of a Compliant Polymer Interface between Standard Fibers and Nanophotonic Waveguides. , 2015, , .		17
8	Flip chip assembly with sub-micron 3D re-alignment via solder surface tension. , 2015, , .		17
9	A Metamaterial Converter Centered at 1490nm for Interfacing Standard Fibers to Nanophotonic Waveguides. , 2016, , .		15
10	Toward High-Yield 3D Self-Alignment of Flip-Chip Assemblies via Solder Surface Tension. , 2016, , .		12
11	A compliant polymer interface with 1.4dB loss between standard fibers and nanophotonic waveguides. , 2016, , .		11
12	Formation of nanometer-thick delaminated amorphous carbon layer by two-step plasma processing of methacrylate-based polymer. Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics, 2015, 33, .	1.2	8
13	Sub-Micron Bondline-Shape Control in Automated Assembly of Photonic Devices. , 2016, , .		8
14	High-Throughput Photonic Packaging. , 2017, , .		5
15	Significance of plasma-photoresist interactions for atomic layer etching processes with extreme ultraviolet photoresist. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	2.1	4
16	Photonic metacrystal: design methodology and experimental characterization. Optics Express, 2022, 30, 7612.	3.4	3
17	Breaking the mold of photonic packaging. , 2018, , .		2
18	Towards co-packaging of photonics and microelectronics in existing manufacturing facilities. , 2018, , .		2